

UNITED STATES

DECLARATION FOR PATENT APPLICATION Docket No. NEKA 18.612

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE, AND PROCESSING SYSTEM AND SEMICONDUCTOR DEVICE

the specification of which

(check one) ☒ is attached hereto.

☐ was filed on _____ as

Application Serial No. _____

and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by an amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)	Country	Filing Date	Priority Claimed
P2000-131626	Japan	28/04/2000	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
(Number)	(Country)	(Day/Month/Year Filed)	Yes No
(Number)	(Country)	(Day/Month/Year Filed)	Yes No
(Number)	(Country)	(Day/Month/Year Filed)	Yes No

I hereby claim the benefit under Title 35, United State Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

(Application Serial No.)	(Filing Date)	(Status - patented, pending, abandoned)
(Application Serial No.)	(Filing Date)	(Status - patented, pending, abandoned)

I hereby appoint as my attorney and agent Aaron B. Karas, Reg. No. 18,923, Samson Helfgott, Reg. No. 23,072 and Emma Shleifer, Reg. No. 29,734 to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

Address all correspondence to:

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60th Floor
Empire State Building
New York, New York 10118-0110
Telephone No. (212) 643-5000

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor Yoshihisa Matsubara
Inventor's signature *Yoshihisa Matsubara* Date March 22, 2001
Residence Tokyo, Japan Citizenship Japan
Post Office Address c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku, Tokyo, Japan

Full name of second joint inventor, if any Toshiyuki Takewaki
Second Inventor's signature *Toshiyuki Takewaki* Date March 22, 2001
Residence Tokyo, Japan Citizenship Japan
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Full name of third joint inventor, if any Manabu Iguchi
 Third Inventor's signature Manabu Iguchi Date March 22, 2001
 Residence Tokyo, Japan Citizenship Japan
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Full name of fourth joint inventor, if any _____
 Fourth Inventor's signature _____ Date _____
 Residence _____ Citizenship _____
 Post Office Address _____

Full name of fifth joint inventor, if any _____
 Fifth Inventor's signature _____ Date _____
 Residence _____ Citizenship _____
 Post Office Address _____

Full name of sixth joint inventor, if any _____
 Sixth Inventor's signature _____ Date _____
 Residence _____ Citizenship _____
 Post Office Address _____

Full name of seventh joint inventor, if any _____
 Seventh Inventor's signature _____ Date _____
 Residence _____ Citizenship _____
 Post Office Address _____

Full name of eighth joint inventor, if any _____
 Eighth Inventor's signature _____ Date _____
 Residence _____ Citizenship _____
 Post Office Address _____

Full name of ninth joint inventor, if any _____
 Ninth Inventor's signature _____ Date _____
 Residence _____ Citizenship _____
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Witness:

Hitoshi Ukai

Hitoshi Ukai

Akira Muto

Akira Muto

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Yoshihisa MATSUBARA, et al.**

Filed : Concurrently herewith

For : **METHOD FOR MANUFACTURING....**

Serial No. : Concurrently herewith

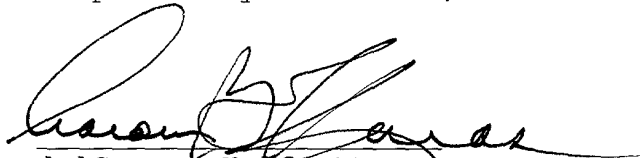
Assistant Commissioner of Patents
Washington, D.C. 20231

SUB-POWER OF ATTORNEY

S I R:

I, Aaron B. Karas, Reg. No. 18,923 attorney of record herein, do hereby grant a sub-power of attorney to Linda S. Chan, Reg. No. 42,400, Harris A. Wolin, Reg. No. 39,432, Brian S. Myers, Reg. No. 46,947 and Michael Markowitz, Reg. No. 30,659 to act and sign in my behalf in the above-referenced application.

Respectfully submitted,



☐ Samson Helfgott

Reg.No. 23,072

☒ Aaron B. Karas

Reg. No. 18,923

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